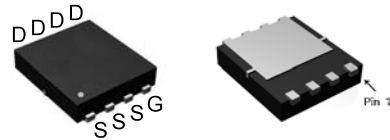


-30V -39A P-Channel Enhancement Mode MOSFET

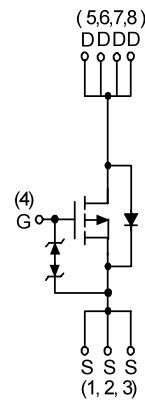
Features

- -30V/-39A,
 $R_{DS(ON)} = 14m\Omega(max.) @ V_{GS} = -10V$
 $R_{DS(ON)} = 24m\Omega(max.) @ V_{GS} = -4.5V$
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)
- ESD protection pass 3KV

Pin Description



DFN3x3-8



P-Channel MOSFET

Applications

- Load Switch.
- Battery Pack Power Management.

-30V -39A P-Channel Enhancement Mode MOSFET

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
Common Ratings			
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 25	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	
I_S	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$ -20	A
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$ -39	
		$T_C=100^\circ\text{C}$ -25	
I_{DM}	Pulsed Drain Current	$T_C=25^\circ\text{C}$ -70 *	
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$ 32.9	W
		$T_C=100^\circ\text{C}$ 13.2	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State 3.8	$^\circ\text{C/W}$
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$ -12 ^b	A
		$T_A=70^\circ\text{C}$ -9.8 ^b	
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$ 3.1	W
		$T_A=70^\circ\text{C}$ 2	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	$t \leq 10\text{s}$ 40	$^\circ\text{C/W}$
		Steady State 75	
I_{AS}^a	Avalanche Current, Single pulse	$L=0.5\text{mH}$ 18	A
E_{AS}^a	Avalanche Energy, Single pulse	$L=0.5\text{mH}$ 81	mJ

Note * : Current limited by bond wire.

Note a : UIS tested and pulse width are limited by maximum junction temperature 150°C
 (initial temperature $T_J = 25^\circ\text{C}$).

Note b : $t < 10\text{s}$.

-30V -39A P-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

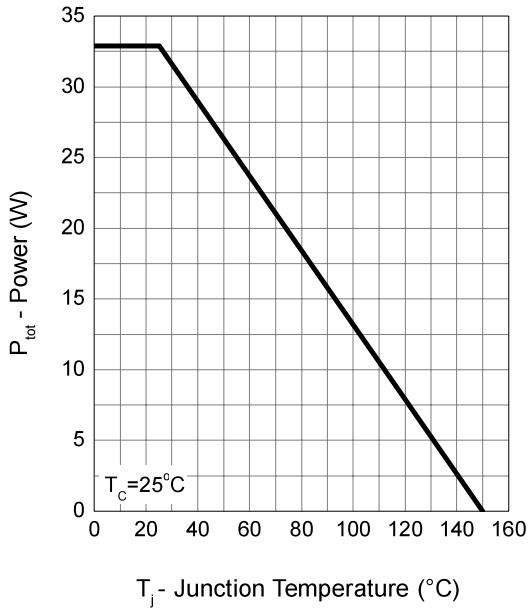
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=-250\mu A$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24V, V_{GS}=0V$	-	-	-1	μA
		$T_J=85^\circ\text{C}$	-	-	-30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	-1.3	-1.8	-2.3	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$	-	-	± 10	μA
$R_{DS(ON)}^c$	Drain-Source On-state Resistance	$V_{GS}=-10V, I_{DS}=-20A$	-	11	14	m Ω
		$V_{GS}=-4.5V, I_{DS}=-10A$	-	18	24	
Diode Characteristics						
V_{SD}^c	Diode Forward Voltage	$I_{SD}=-1A, V_{GS}=0V$	-	-0.7	-1	V
t_{rr}^d	Reverse Recovery Time	$I_{SD}=-20A, dI_{SD}/dt=100A/\mu s$	-	20	-	ns
Q_{rr}^d	Reverse Recovery Charge		-	8	-	nC
Dynamic Characteristics^d						
R_g	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	9	-	Ω
C_{iss}	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=-15V,$ Frequency=1.0MHz	-	1380	-	pF
C_{oss}	Output Capacitance		-	280	-	
C_{riss}	Reverse Transfer Capacitance		-	217	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=-15V, R_L=15\Omega,$ $I_{DS}=-1A, V_{GEN}=-10V,$ $R_G=6\Omega$	-	11	-	ns
t_r	Turn-on Rise Time		-	11	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	101	-	
t_f	Turn-off Fall Time		-	60	-	
Gate Charge Characteristics^d						
Q_g	Total Gate Charge	$V_{DS}=-15V, V_{GS}=-10V,$ $I_{DS}=-20A$	-	30	-	nC
Q_{gs}	Gate-Source Charge		-	1.2	-	
Q_{gd}	Gate-Drain Charge		-	11	-	

Note c : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

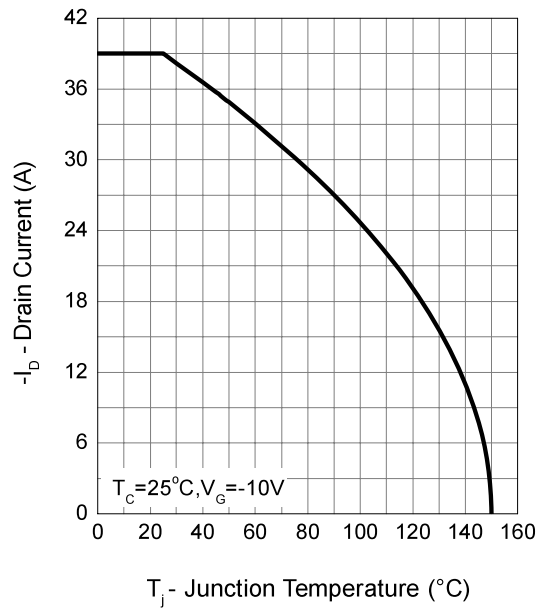
Note d : Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

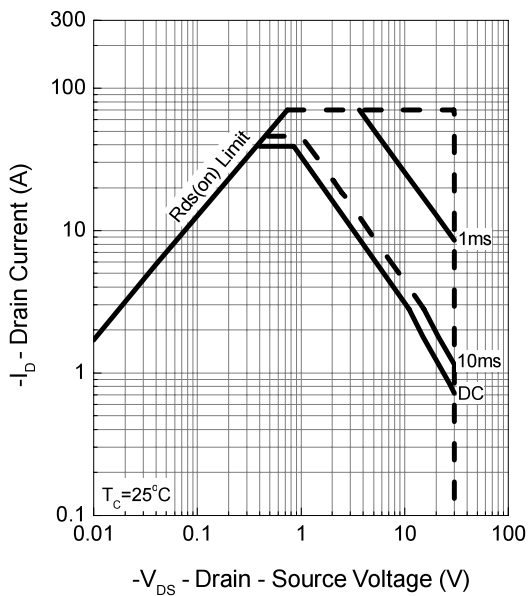
Power Dissipation



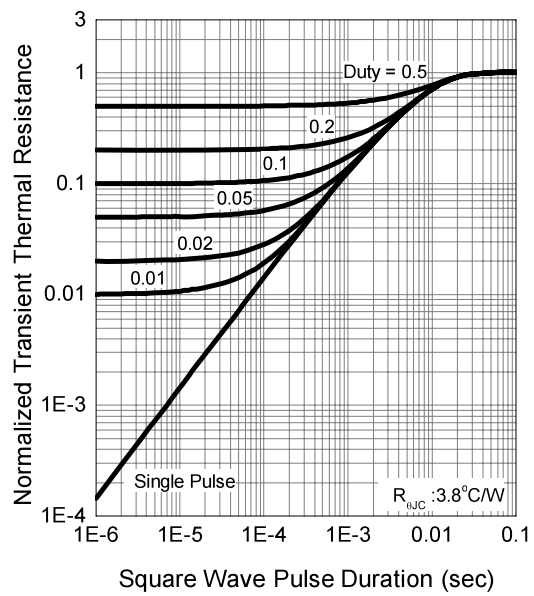
Drain Current



Safe Operation Area

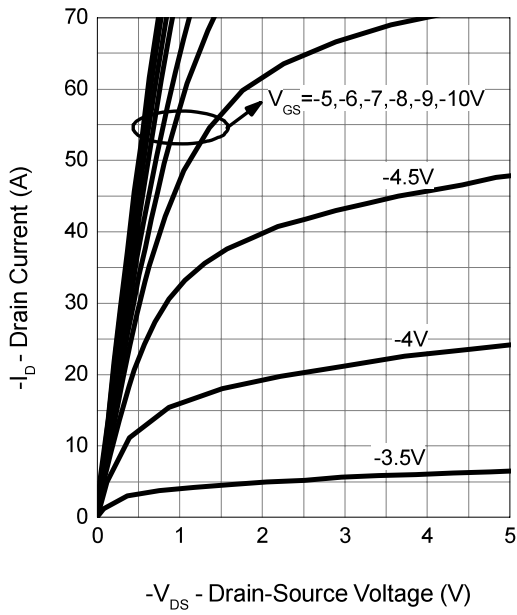


Thermal Transient Impedance

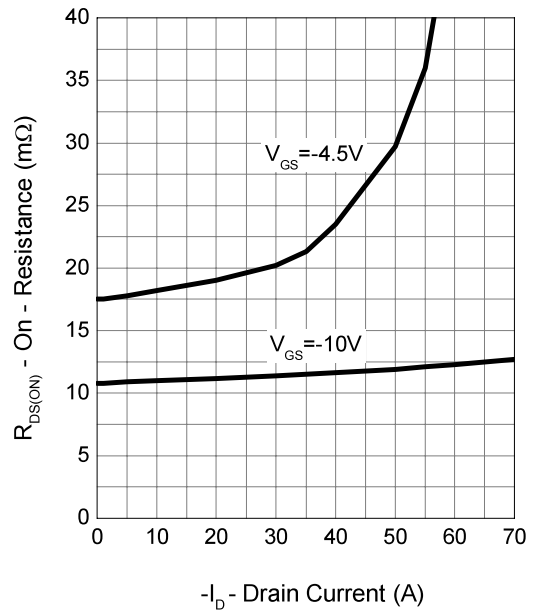


Typical Operating Characteristics (Cont.)

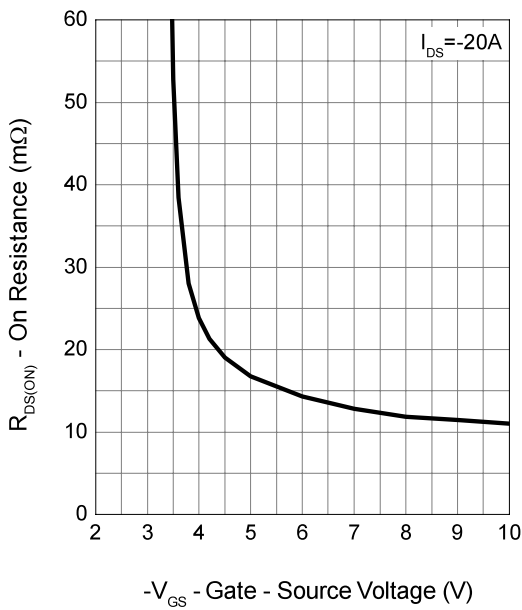
Output Characteristics



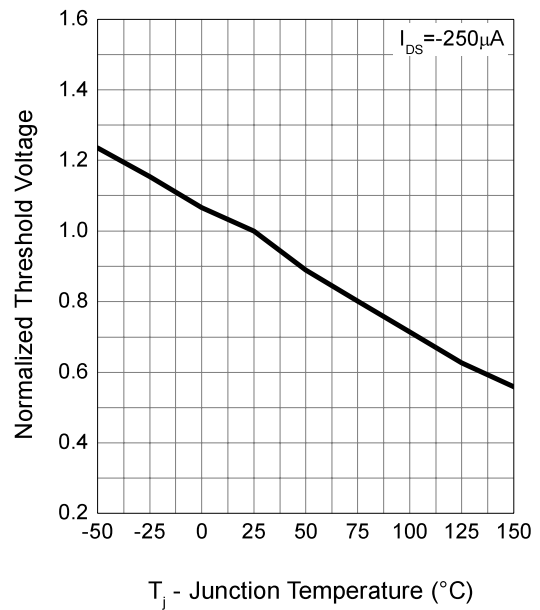
Drain-Source On Resistance



Gate-Source On Resistance

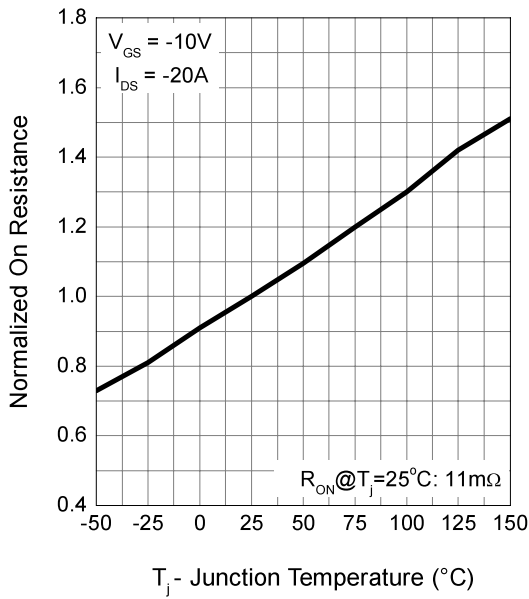


Gate Threshold Voltage

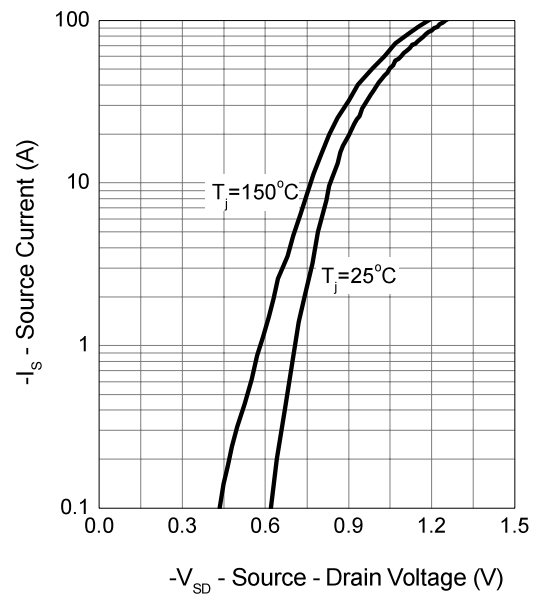


Typical Operating Characteristics (Cont.)

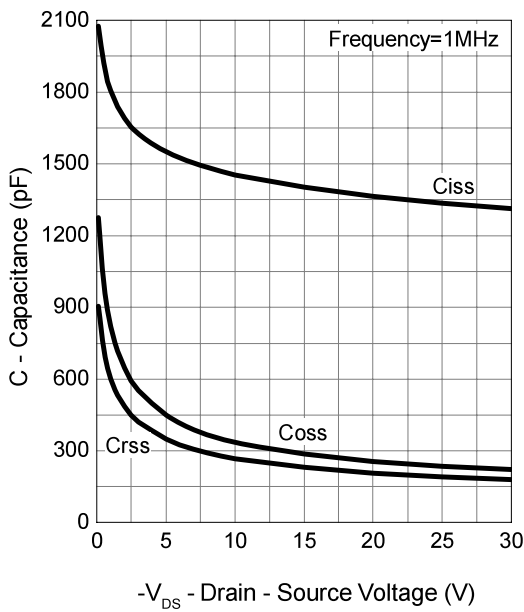
Drain-Source On Resistance



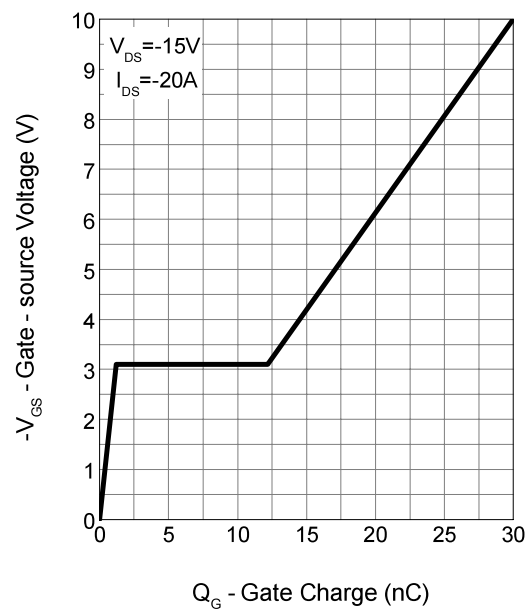
Source-Drain Diode Forward



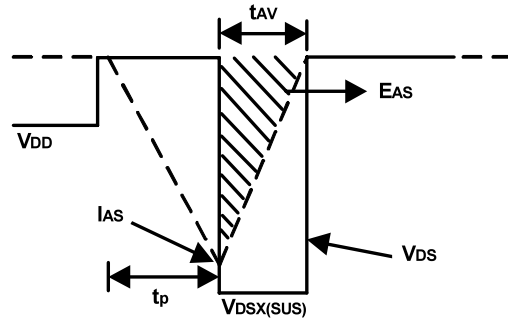
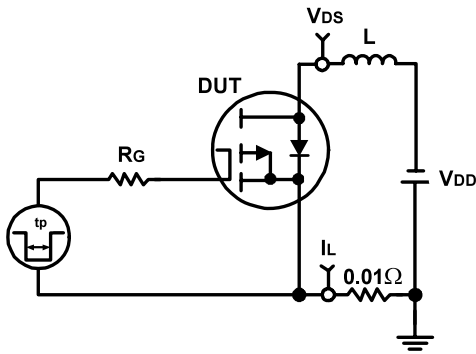
Capacitance



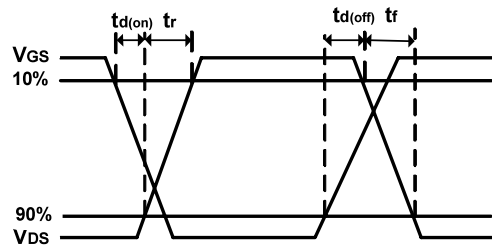
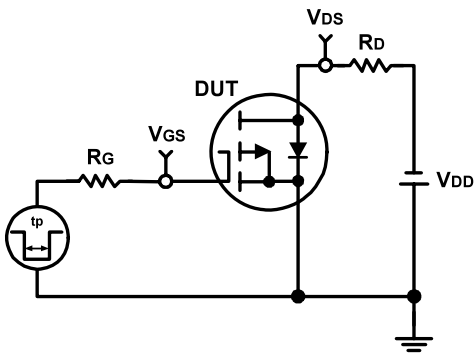
Gate Charge



Avalanche Test Circuit and Waveforms



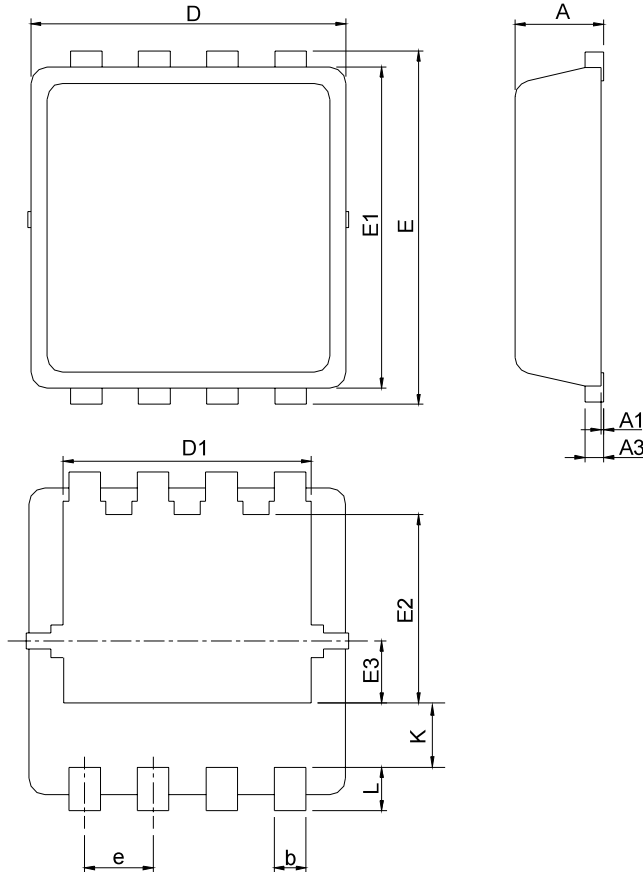
Switching Time Test Circuit and Waveforms



-30V -39A P-Channel Enhancement Mode MOSFET

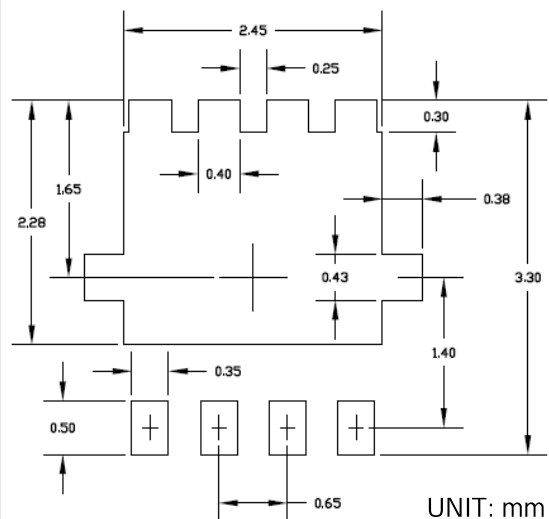
Package Information

DFN3x3-8

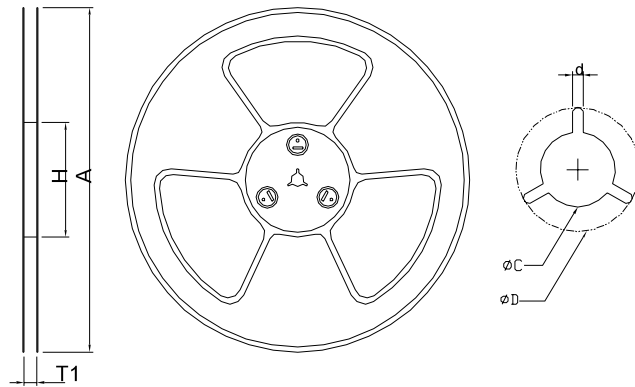
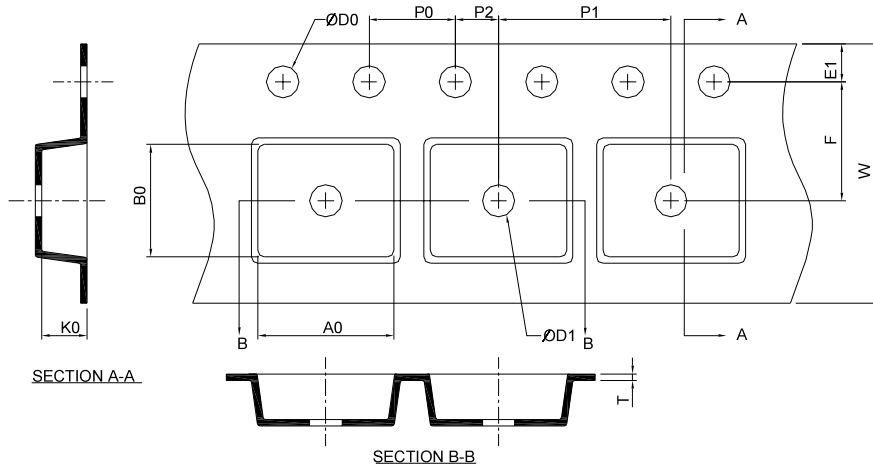


SYMBOL	DFN3x3-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.80	1.00	0.031	0.039
A1	0.00	0.05	0.000	0.002
A3	0.10	0.25	0.004	0.010
b	0.24	0.35	0.009	0.014
D	2.90	3.10	0.114	0.122
D1	2.25	2.45	0.089	0.096
E	3.10	3.30	0.122	0.130
E1	2.90	3.10	0.114	0.122
E2	1.65	1.85	0.065	0.073
E3	0.56	0.58	0.022	0.023
e	0.65 BSC		0.026 BSC	
K	0.475	0.775	0.019	0.031
L	0.30	0.50	0.012	0.020

RECOMMENDED LAND PATTERN



Carrier Tape & Reel Dimensions

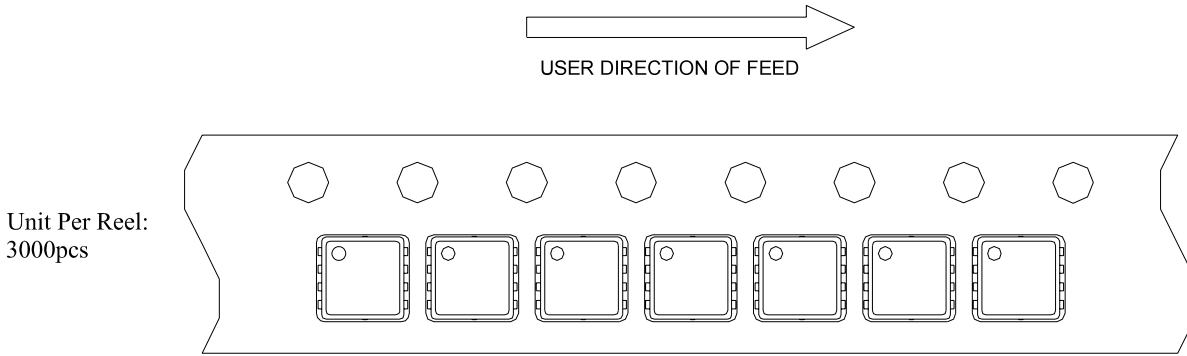


Application	A	H	T1	C	d	D	W	E1	F
DFN3x3-8	178.0±2.00	50 MIN.	8.4+2.00-0.00	13.0+0.50-0.20	1.5 MIN.	20.2 MIN.	8.0±0.20	1.75±0.10	3.5±0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0±0.10	4.0±0.10	2.0±0.05	1.5+0.10-0.00	1.5 MIN.	0.6+0.00-0.40	3.35±0.20	3.35±0.20	1.30±0.20

(mm)

Taping Direction Information

DFN3x3-8



Classification Profile

